

## 1. Product Features

### 1.1 Electrical features

- $V_{CES}=1200V$
- $I_{C\ nom}=200A / I_{CRM}=400A$
- Low switching losses
- Low inductance
- Fast switching and short tail current
- High power and thermal cycling capability

### 1.2 Mechanical features

- $Al_2O_3$  substrate with low thermal resistance
- Copper base plate



Figure1 IGBT Module

## 2. Typical Applications

- High Frequency Switching Application
- Motor drives
- UPS system

## 3. Description

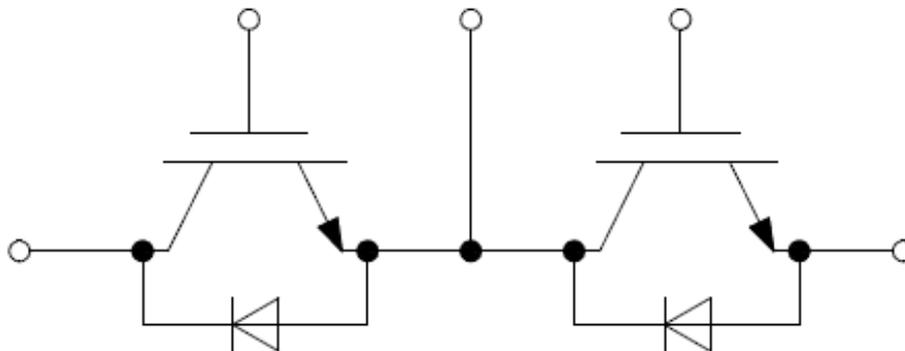


Figure 2 Half Bridge

## 4. IGBT, Inverter

### 4.1 Maximum rated values

Parameter	Note or test condition	Symbol	Values	Unit
Collector-emitter voltage 集电极—发射极间电压	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	1200	V
Continuous DC collector current 连续集电极电流	$T_C = 100^{\circ}\text{C}, T_{vj\ max} = 150^{\circ}\text{C}$	$I_{C\ nom}$	200	A
Repetitive peak collector current 集电极峰值电流	$t_P = 1\ \text{ms}$	$I_{CRM}$	400	A
Total power dissipation 总功率损耗	$T_C = 25^{\circ}\text{C}, T_{vj\ max} = 175^{\circ}\text{C}$	$P_{tot}$	1250	W
Gate-emitter peak voltage 栅极—发射极峰值电压		$V_{GES}$	+/- 20	V

### 4.2 Characteristic value

Parameter	Note or test condition	Symbol	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter saturation voltage 集电极—发射极饱和电压	$I_C = 200\text{A}, V_{GE} = 15\text{V}$	$V_{CE,sat}$		$T_{vj} = 25^{\circ}\text{C}$	1.63	V
				$T_{vj} = 125^{\circ}\text{C}$	1.86	V
				$T_{vj} = 150^{\circ}\text{C}$	1.92	V
Gate threshold voltage 栅极阈值电压	$I_C = 2\text{mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$	$V_{GE,th}$	5.0	5.5	6.0	V
Gate charge 栅极电荷	$V_{GE} = -15\text{V} \dots +15\text{V}$	$Q_G$		1.96		$\mu\text{C}$
Internal gate resistor 内部栅极电阻	$T_{vj} = 25^{\circ}\text{C}$	$R_{Gint}$		1.50		$\Omega$
Input capacitance 输入电容	$f=1\text{MHz}, T_{vj}=25^{\circ}\text{C}, V_{CE}=25\text{V}, V_{GE}=0\text{V}$	$C_{ies}$		55.2		nF
Reverse transfer capacitance 反向传输电容	$f=1\text{MHz}, T_{vj}=25^{\circ}\text{C}, V_{CE}=25\text{V}, V_{GE}=0\text{V}$	$C_{res}$		0.44		nF
Collector-emitter cut-off current 集电极-发射极截止电流	$V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}, T_{vj} = 25^{\circ}\text{C}$	$I_{CES}$			2	mA
Gate-emitter leakage current 栅极-发射极漏电流	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}, T_{vj} = 25^{\circ}\text{C}$	$I_{GES}$			200	nA
Turn-on delay time, inductive load 开通延迟时间	$I_C = 200\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = +15/-15\text{V}$ $R_{G,on} = 4.1\Omega$	$t_{d,on}$		$T_{vj} = 25^{\circ}\text{C}$	0.13	$\mu\text{s}$
				$T_{vj} = 125^{\circ}\text{C}$	0.14	$\mu\text{s}$
				$T_{vj} = 150^{\circ}\text{C}$	0.14	$\mu\text{s}$
Rise time, inductive load 上升时间	$I_C = 200\text{A}, V_{CE} = 600\text{V}$ $V_{GE} = +15/-15\text{V}$ $R_{G,on} = 4.1\Omega$	$t_r$		$T_{vj} = 25^{\circ}\text{C}$	0.06	$\mu\text{s}$
				$T_{vj} = 125^{\circ}\text{C}$	0.07	$\mu\text{s}$
				$T_{vj} = 150^{\circ}\text{C}$	0.07	$\mu\text{s}$

(table continues...) 待续

Parameter	Note or test condition	Symbol	Values			Unit	
			Min.	Typ.	Max.		
Turn-off delay time, inductive load 关断延迟时间	$I_C = 200A, V_{CE} = 600V$ $V_{GE} = +15/-15V$ $R_{G,off} = 4.1\Omega$	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	$t_{d,off}$		0.31		us
					0.34		us
					0.34		us
Fall time, inductive load 下降时间	$I_C = 200A, V_{CE} = 600V$ $V_{GE} = +15/-15V$ $R_{G,off} = 4.1\Omega$	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	$t_f$		0.22		us
					0.25		us
					0.27		us
Turn-on energy loss per pulse 开通损耗能量	$I_C = 200A, V_{CE} = 600V, L_s = 20nH$ $V_{GE} = +15/-15V, di/dt = 2200A/\mu s$ $R_{G,on} = 4.1\Omega (T_{vj} = 150^\circ C)$	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	$E_{on}$		14.10		mJ
					20.90		mJ
					24.38		mJ
Turn-off energy loss per pulse 关断损耗能量	$I_C = 200A, V_{CE} = 600V, L_s = 20nH$ $V_{GE} = +15/-15V, dv/dt = 7500V/\mu s$ $R_{G,off} = 4.1\Omega (T_{vj} = 150^\circ C)$	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	$E_{off}$		13.52		mJ
					14.58		mJ
					15.90		mJ
SC data 短路数据	$V_{GE} \leq 15V, V_{CC} = 600V, t_P \leq 8 \mu s, T_{vj} = 150^\circ C,$ $C_{GE} = 0.0\mu F, V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$	$I_{sc}$		1160		A	
Thermal resistance, junction to case 结-外壳热阻	Per IGBT	$R_{th,jc}$			0.12	K/W	

## 5. Diode

### 5.1 Maximum rated values

Parameter	Note or test condition	Symbol	Values	Unit
Repetitive peak reverse voltage 反向重复峰值电压	$T_{vj} = 25^\circ C$	$V_{RRM}$	1200	V
Continuous DC forward current 连续正向直流电流		$I_F$	200	A
Repetitive peak forward current 正向重复峰值电流	$t_P = 1 ms$	$I_{FRM}$	400	A

### 5.2 Characteristic value

Parameter	Note or test condition	Symbol	Values			Unit
			Min.	Typ.	Max.	
Forward voltage 正向电压	$I_F = 200A, V_{GE} = 0V$	$V_F$		2.10	2.42	V
				2.08		V
				1.99		V

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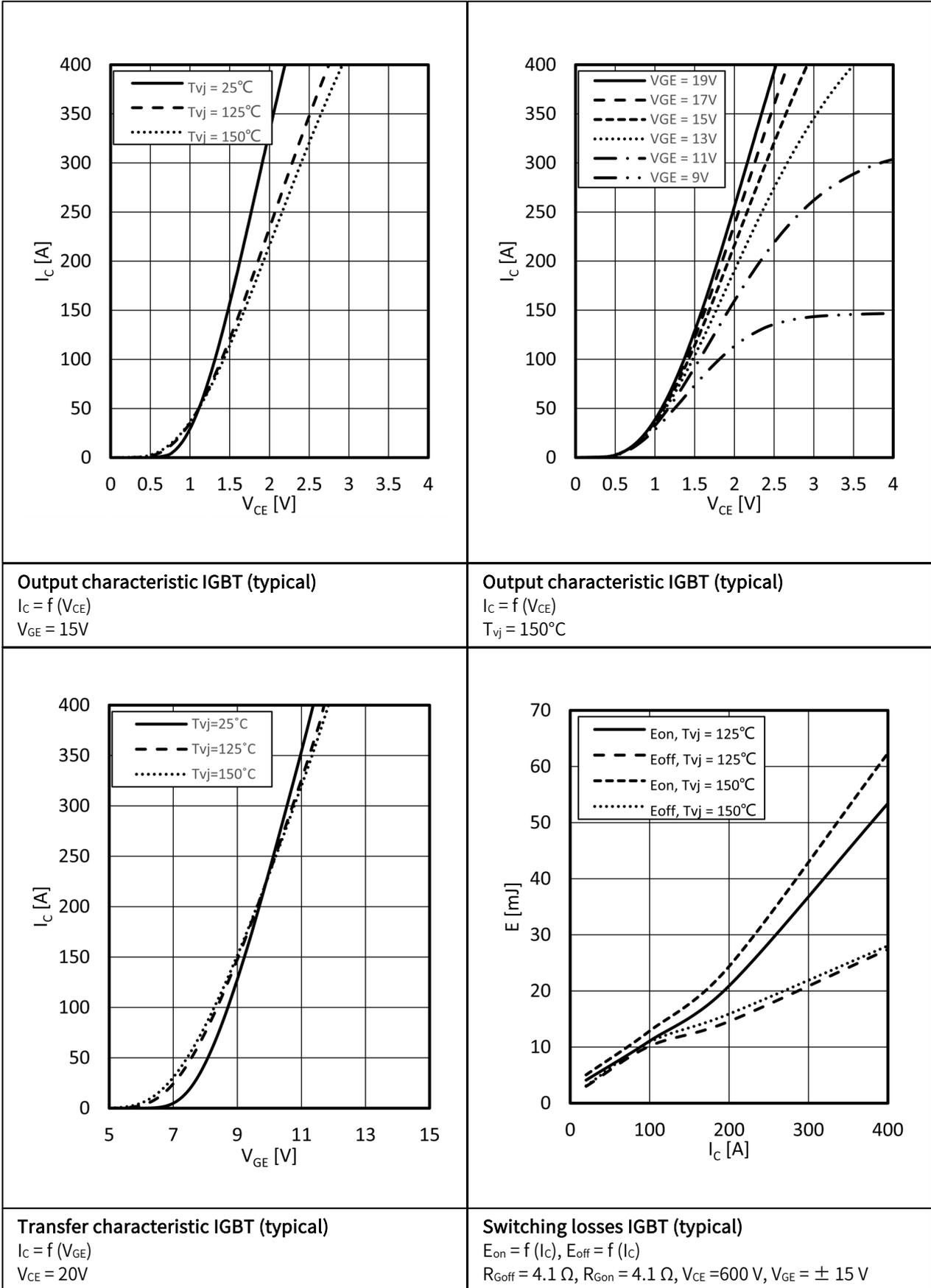
Parameter	Note or test condition		Symbol	Values			Unit
				Min.	Typ.	Max.	
Peak reverse recovery current 反向恢复峰值电流	$I_F = 200A, V_R = 600V$ $V_{GE} = -15V, -di_F/dt = 1140 A/\mu s$ ( $T_{vj}=150^\circ C$ )	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	$I_{RM}$		159 171 179		A A A
Recovered charge 恢复电荷	$I_F = 200A, V_R = 600V$ $V_{GE} = -15V, -di_F/dt = 1140 A/\mu s$ ( $T_{vj}=150^\circ C$ )	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	$Q_r$		13.9 18.8 25.2		$\mu C$ $\mu C$ $\mu C$
Reverse recovery energy 反向恢复损耗 (每脉冲)	$I_F = 200A, V_R = 600V$ $V_{GE} = -15V, -di_F/dt = 1140 A/\mu s$ ( $T_{vj}=150^\circ C$ )	$T_{vj} = 25^\circ C$ $T_{vj} = 125^\circ C$ $T_{vj} = 150^\circ C$	$E_{rec}$		3.50 4.40 6.00		mJ mJ mJ
Thermal resistance, junction to case 结-外壳热阻	Per diode		$R_{th,jc}$			0.20	K/W

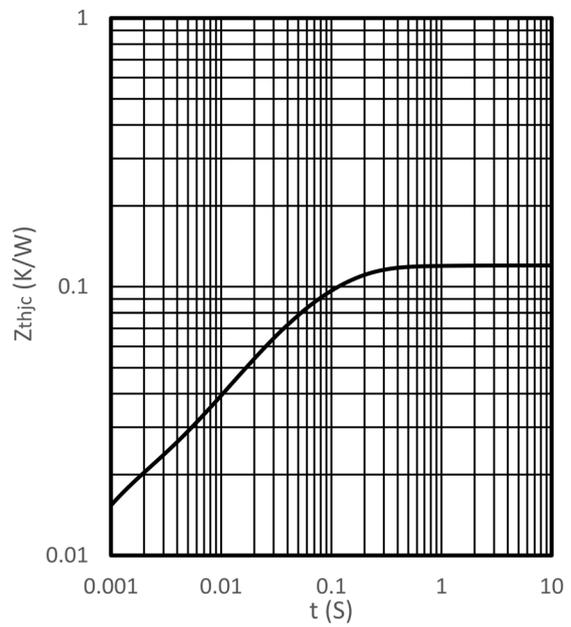
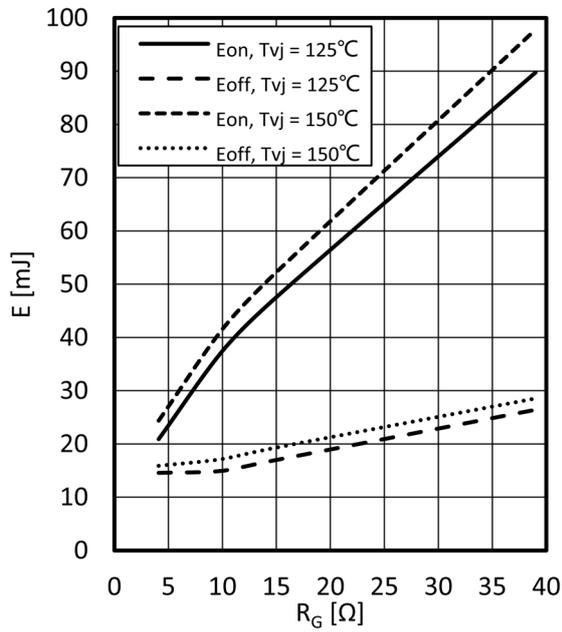
## 6. Module

### 6.1 Characteristic value

Parameter	Note or test condition	Symbol	Values			Unit
			Min.	Typ.	Max.	
Isolation Voltage 隔离电压	RMS, f=50HZ,1min	$V_{ISOL}$			4000	V
Stray inductance module 杂散电感		$L_{SCE}$		20		nH
Operation Junction Temperature 结温		$T_{jop}$	-40		150	$^\circ C$
Storage Temperature Range 存储温度范围		$T_{stg}$	-40		125	$^\circ C$
Mounting Torque 安装扭矩	Screw M6	M	3		6	N.m
Terminal Connection Torque 端子连接扭矩	Screw M6	M	2.5		5	N.m
Weight of Module 重量		G		340		g

## 7. Characteristics diagrams





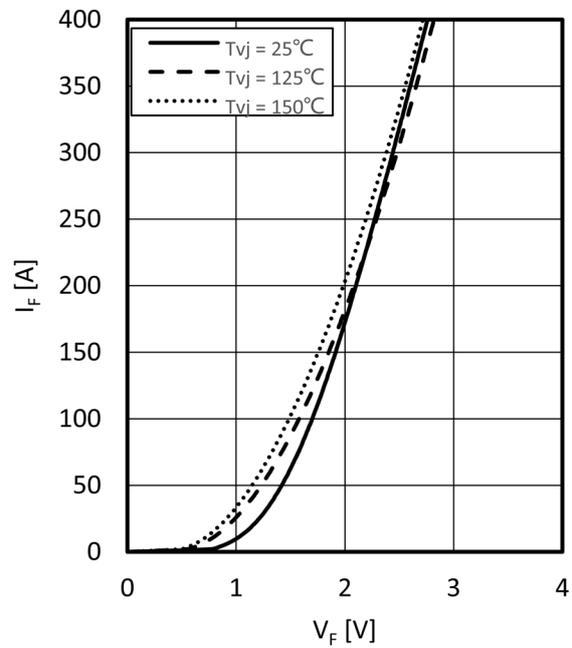
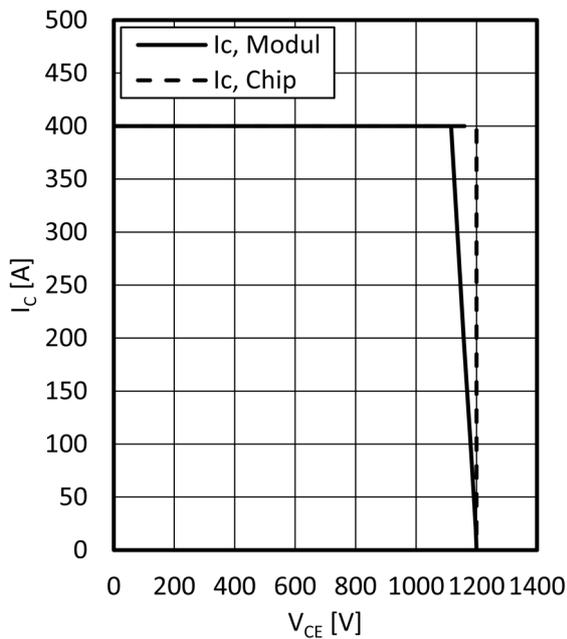
**Switching losses IGBT (typical)**

$$E_{on} = f(R_G), E_{off} = f(R_G)$$

$$I_C = 200 \text{ A}, V_{CE} = 600 \text{ V}, V_{GE} = \pm 15 \text{ V}$$

**Transient thermal impedance IGBT**

$$Z_{thJC} = f(t)$$



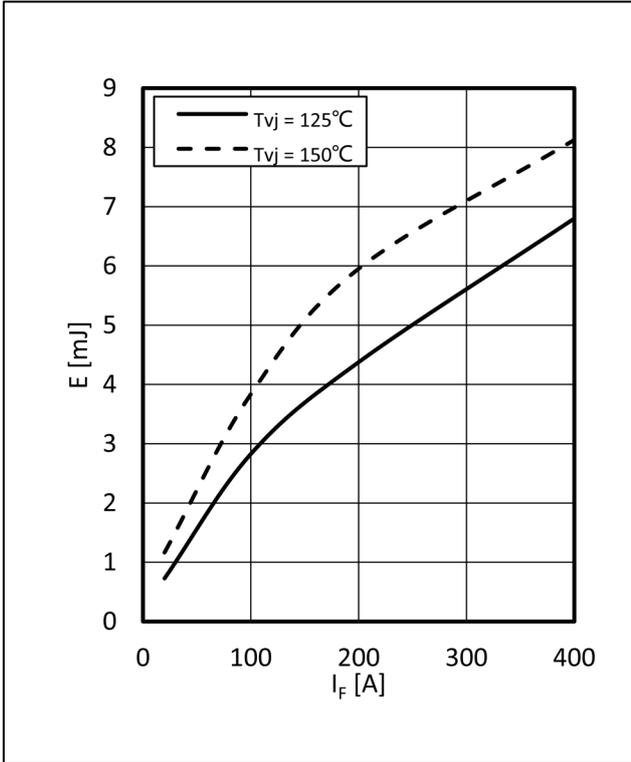
**Reverse bias safe operating area IGBT(RBSOA)**

$$I_C = f(V_{CE})$$

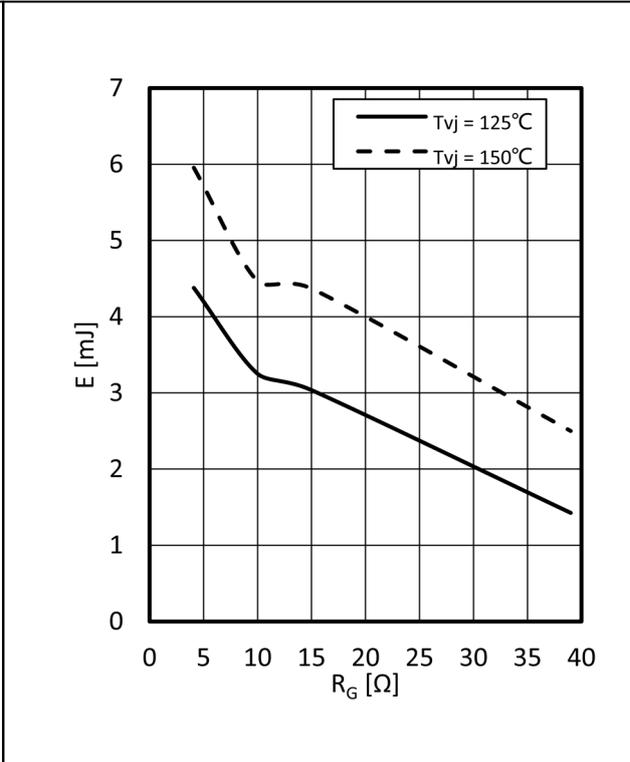
$$V_{GE} = \pm 15 \text{ V}, R_{Goff} = 4.1 \Omega, T_{vj} = 150^\circ\text{C}$$

**Forward characteristic of Diode (typical)**

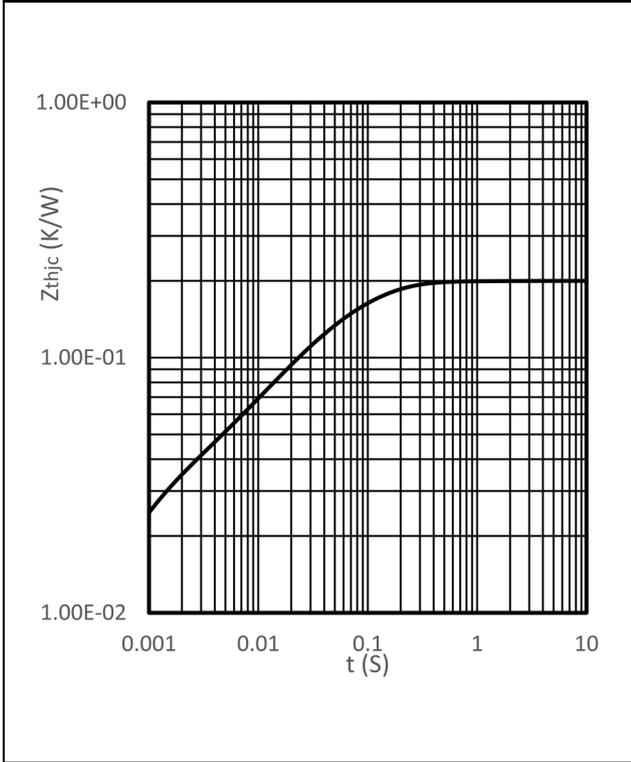
$$I_F = f(V_F)$$



**Switching losses Diode (typical)**  
 $E_{rec} = f(I_F)$   
 $R_{Gon} = 4.1 \Omega, V_{CE} = 600 V$



**Switching losses Diode (typical)**  
 $E_{rec} = f(R_G)$   
 $I_F = 200 A, V_{CE} = 600 V$



**Transient thermal impedance Diode**  
 $Z_{thjC} = f(t)$

### 8. Circuit Diagram

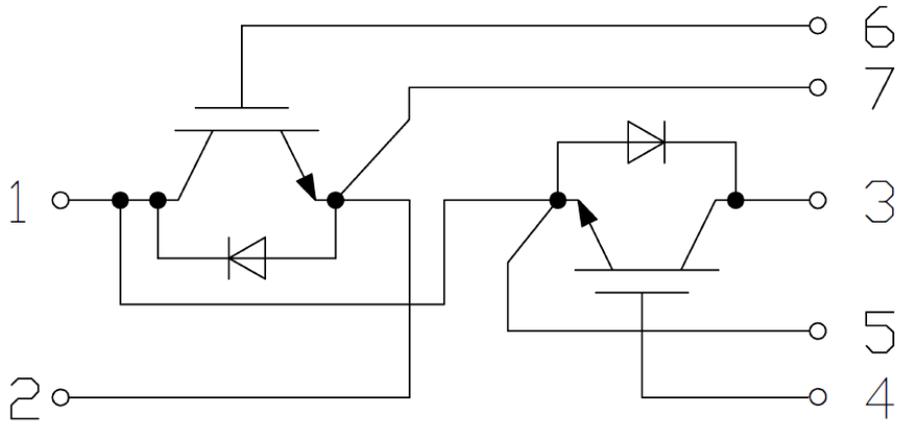


Figure 3

### 9. Package Outlines

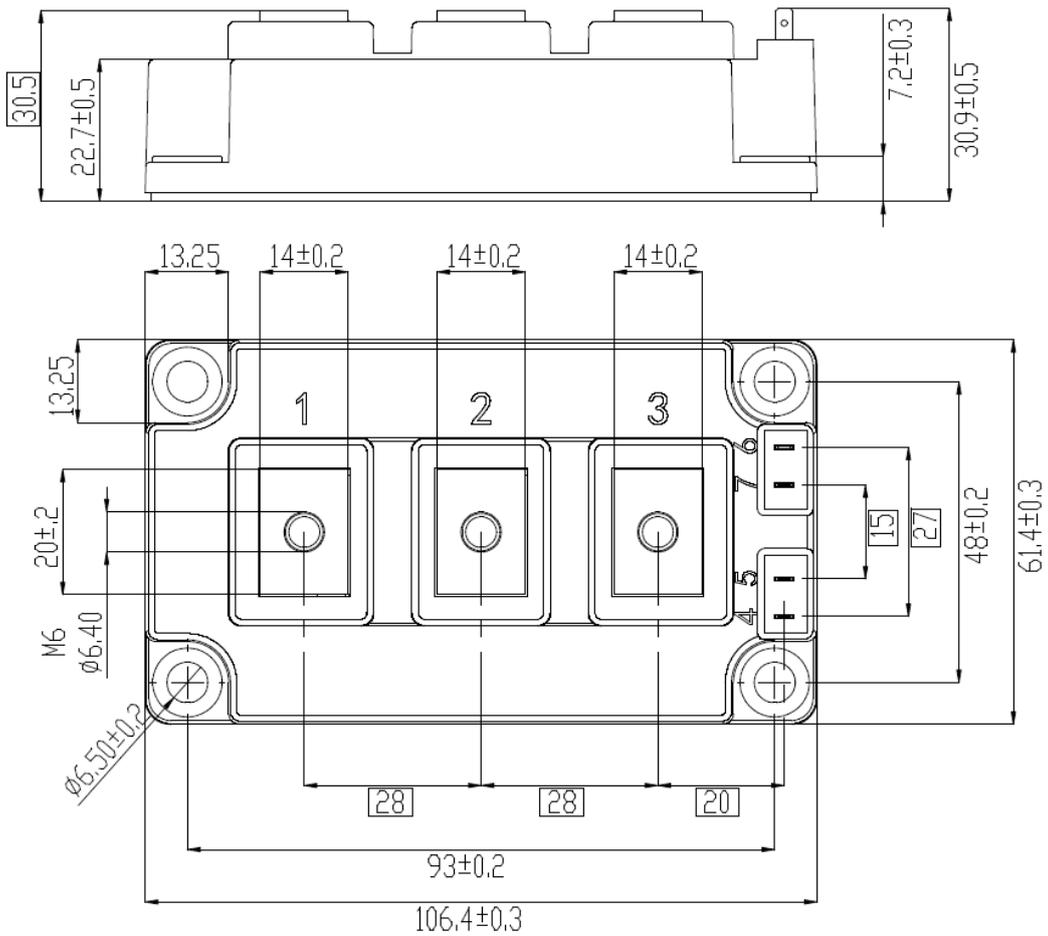


Figure 4